

## Fabrication of Ta<sub>2</sub>O<sub>5</sub>-Si System with Low Density of Interface States and Deep Traps by Plasma Enhanced Liquid Source CVD

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Recently considerable amount of work has been done on Ta<sub>2</sub>O<sub>5</sub> high dielectric constant material, specially its growth, structural and electrical properties are well known [1,2]. However, Ta<sub>2</sub>O<sub>5</sub> has not been investigated so far, in the areas of interface states and deep traps, to the best of our knowledge and therefore is the aim of the present work.

Tantalum penta oxide was deposited by plasma-enhanced LS-CVD from Ta(OC<sub>2</sub>H<sub>5</sub>)<sub>5</sub> source and Au/Ta<sub>2</sub>O<sub>5</sub>/Si MOS structures were fabricated. We have estimated the distribution of interface state density (N<sub>ss</sub>) within the energy level corresponding to the bandgap of Si by using Terman's differentiation method. The results obtained on the Ta<sub>2</sub>O<sub>5</sub>-p-Si system is shown in fig. 1, where N<sub>ss</sub> is as low as  $2.5 \times 10^{11} \text{ cm}^{-2} \cdot \text{eV}^{-1}$  below the fermi level and  $7 \times 10^{11} \text{ cm}^{-2} \cdot \text{eV}^{-1}$  near the midgap. It passes through a peak at about 0.4 eV. The origin of this peak is unknown, but we believe that surface states at the Ta<sub>2</sub>O<sub>5</sub>-Si system are caused by the reaction between the Ta atoms and Silicon dangling bonds.

In order to investigate deep traps in Ta<sub>2</sub>O<sub>5</sub>, we have studied variation in the flat band voltage, V<sub>FB</sub> as a result of the electric field applied to the Au/Ta<sub>2</sub>O<sub>5</sub>/Si MOS diode. In fig [2-a,b] we show the effect of an applied field on the C-V curve. A number of samples investigated in both n-Si (not shown in the figure) and p-Si materials showed negligible variation of C-V curve along the voltage axis (fig 2-a) and only one sample resulted in variation along voltage axis (fig.2-b). This particular sample belongs to a different batch of Ta<sub>2</sub>O<sub>5</sub> growth. The variation in the total charges as shown in fig (3), is related to ionization of the deep traps lying within the band gap of the Ta<sub>2</sub>O<sub>5</sub> layer.

With increasing applied electric fields, the deep traps are ionized almost completely. This is because the variation in Q<sub>ss</sub> comes to a saturation with increase in the applied electric field and at E=10MV/cm, the variation is almost negligible. The total variation in the charges is about  $2.37 \times 10^{-7} \text{ coulomb/cm}^2$  which corresponds to  $1.48 \times 10^{12} / \text{cm}^2$ , equivalent deep trap density. Here it is assumed that the deep traps at the interface and inside the Ta<sub>2</sub>O<sub>5</sub> layer are uniformly distributed such that the defect density calculated at the interface is expected to be the same inside the Ta<sub>2</sub>O<sub>5</sub> film. The other sample which did not show any noticable change in the C-V curve after the application of electric field, results in on order of magnitude lower equivalent deep trap density of  $2.4 \times 10^{11} \text{ cm}^{-2}$ .

Deep traps in the Ta<sub>2</sub>O<sub>5</sub> can be caused by native defects such as tantalum and oxygen vacancies and foreign impurities such as carbon. The possibility of deep traps caused by carbon impurities is large due to the fact that the Ta<sub>2</sub>O<sub>5</sub> is grown from Ta(OC<sub>2</sub>H<sub>5</sub>)<sub>5</sub>, which contains carbon. A proper identification of defects in Ta<sub>2</sub>O<sub>5</sub> has, yet to be done.

Next, we also investigated the effect of an applied electric field on the interface state density, obtained by the Terman method (fig. 4). Variation in the N<sub>ss</sub> is found to be negligible in both the samples (A,B). This is because our as-grown C-V characteristics are very well defined, near ideal and are parallel to ideal C-V curve.

In conclusion, these results strongly suggest low interface state density and deep level defects in Ta<sub>2</sub>O<sub>5</sub>-Si system. Hence Ta<sub>2</sub>O<sub>5</sub> films grown by PE-LS-CVD are of much importance as an oxide capacitors in I.C. technology.

- 1) H. Shinriki and M. Nakata: IEEE Trans. on Electron Devices 38 (1991) 455.
- 2) P.A. Murawala et al; Jpn. J. Appl. Phys. 32, 368-375 (1993).

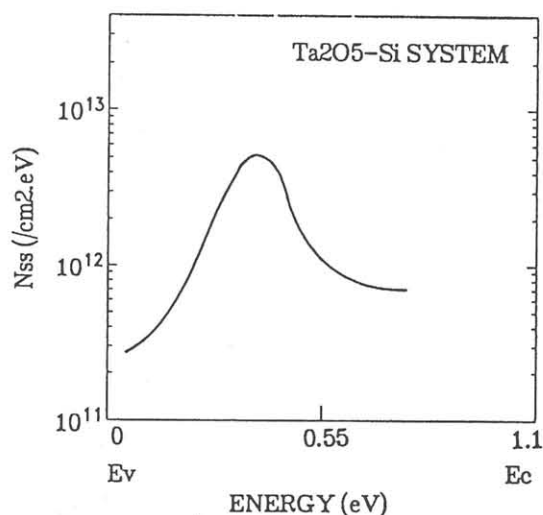


Fig.1 Distribution of interface state density in the  $\text{Ta}_2\text{O}_5$ -Si system, determined by the Terman differentiation procedure.

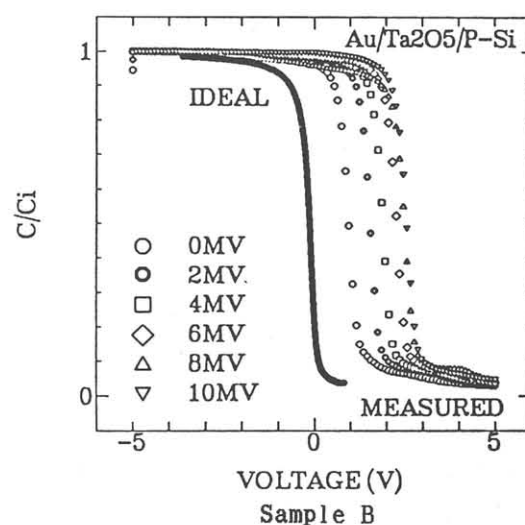
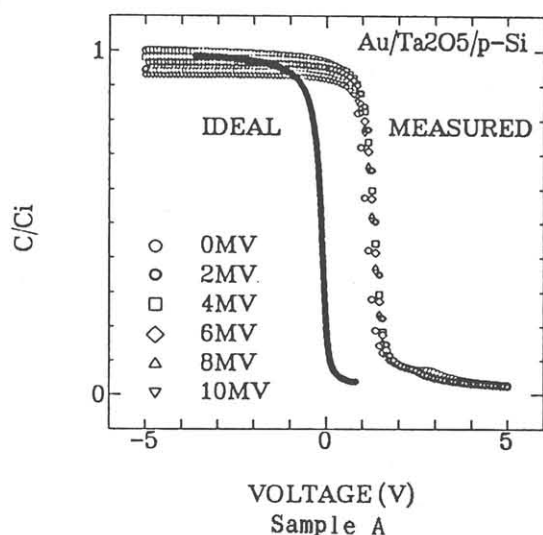


Fig.2 Effect of applied electric field on the C-V characteristics of  $\text{Au/Ta}_2\text{O}_5/\text{p-Si}$ . Results of two different samples A and B is shown.

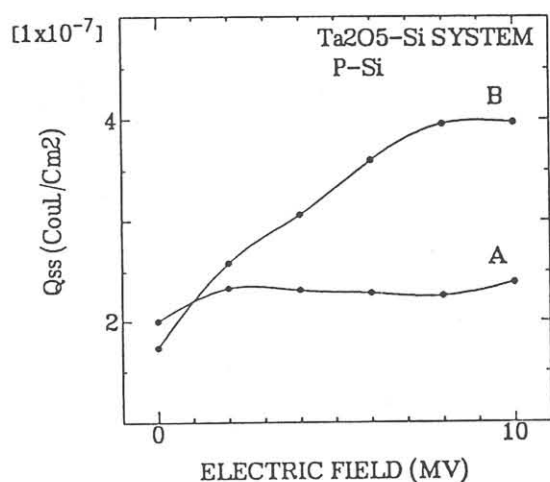


Fig.3 Variation of total charges in  $\text{Ta}_2\text{O}_5$  film due to applied electric field.

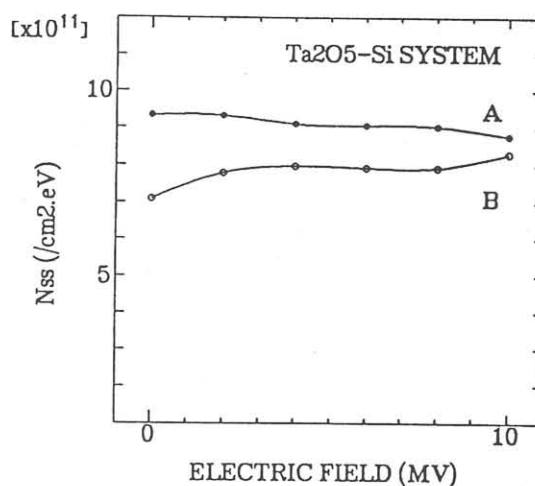


Fig.4 Effect of applied electric fields on the surface state density of  $\text{Ta}_2\text{O}_5$ -Si system.